Refine Search

Search Results -

Terms	Documents
"first conductor" and "second terminal surface" and "third conductor" and "chip" and "resin package" and "third conductor"	2

Database:

US Pre-Grant Publication Full-Text Database
US Patents Full-Text Database
US OCR Full-Text Database
EPO Abstracts Database
JPO Abstracts Database
Derwent World Patents Index
IBM Technical Disclosure Bulletins

Search: L10

Refine Search

Recall Text   Clear   Interrupt

Search History

DATE: Friday, September 09, 2005   Printable Copy   Create Case

Set Name side by side	Query	Hit Count	Set Name result set
DB=PGPB; PLUR=YES; OP=OR			
L10	"first conductor" and "second terminal surface" and "third conductor" and "chip" and "resin package" and "third conductor"	2	L10
DB=JPAB; PLUR=YES; OP=OR			
L9	"chip or die" and ("first conductor" or "first terminal" or "first bonding pad" or "first electrode")	0	L9
DB=EPAB; PLUR=YES; OP=OR			
L8	"chip or die" and ("first conductor" or "first terminal" or "first bonding pad" or "first electrode")	0	L8
DB=USPT; PLUR=YES; OP=OR			
L7	L6 and ((terminal or electrode) near15 ((chip or die) near8 ("upper surface" or "lower surface" or "first surface" or "second surface")))	77	L7
L6	L5 and (die or chip)	3111	L6

L5	L4 and ("third conductor" or "third terminal" or "third bonding pad" or "third electrode")	12883	L5
L4	L3 and ("second conductor" or "second terminal" or "second bonding pad" or "second electrode")	65101	L4
L3	("first conductor" or "first terminal" or "first bonding pad" or "first electrode")	73858	L3
L2	"chip or die" and ("first conductor" or "first terminal" or "first bonding pad" or "first electrode")	0	L2
L1	4945398	23	L1

END OF SEARCH HISTORY